ASSOCIATION CONNECTING ELECTRONICS INDUSTRIES® International and Par	PC. Bannockl	burn. Illinois. A	Il rights reserved untions.	under both	This docume level parts, t	ent is a declaration en declaration	on of the su compasses	bstances v s all lower	within the manufactu level materials for w	rer listed i which the r	tem. Note: i nanufacture	if the item is an as r has engineering	sembly with low responsibility.	
				Form Type Distribute					ials and Mfg Information					
upplier Information														
Company name* Comp			ompany unique ID			Unique ID Authority				Respon	Response Date*			
asemi										2024-04-30				
Title - Contact			ct				Phone - Contact*				Email - Contact*			
Product-Env-Stewards Product Env			wiro Compliance			NA				Product-Env-Stewards@onsemi.com				
Authorized Representative* Title - Repr			presentative			Phone - Representative*				Email - Representative*				
Product-Env-Stewards Product			oduct Enviro Compliance			NA				Produc	Product-Env-Stewards@onsemi.com			
Requester Item Number	Mfr Iten	n Number	Mfr Item Name			Effective Date	Version	ion Manufacturing Site			Weight*	UOM	Unit Type	
	H11AA	11AA1SVM 6PW TR SMD V		/DE		2024-04-30		L	LITEONFG		464.903	mg	Each	
Ianufacturing Proccess Informa	tion						·					· · ·		
Terminal Plating / Grid Array M	aterial T	Ferminal Base A	Alloy J-STD-020 MSL Rat		L Rating	Peak Proce	Process Body Temperatu		ure Max Time at Peak Tempera		ture Num	ber of Reflow Cyc	cles	
Matte Tin (Sn) - annealed CU Alloy		CU Alloy	1			260 C		С	30 seco		seconds 3			
omments														
vel 1 - maximum time at peak temperat	ure during so	Idering is 10-3	0 seconds											
or more information regarding material	composition	please refer to	page 3											

RoHS Material Composition Declaration				Declaration Type *	Detailed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU	(Pb), Mercury (Hg), Hexavalent Chror	oHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead b), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl thalate (BBP), Dibutyl phthalate (DBP), Disobutyl phthalate (DIBP).									
cadmium, hexavalentchromium, polybrominate contains a RoHS restricted substance inexcess encompass all such components. Supplier certif as of the date that Supplier completes this form Company acknowledges that Supplier may hav independently verified information provided by certification in this paragraph. If the Company a	ed biphenyls and/or polybrominated dip of an applicable quantity limit, please ir ies that it gathered the information it pro- .Supplier acknowledges that Company e relied on informationprovided by othe y others, Supplier agrees that, at a minin and the Supplier enter into a written agre pource of the Supplier's liability and the	henyl ethers (each a " ndicate below which, i ovides in this form us will rely on this certifiers in completing this num, itssuppliers have eement with respect to Company's remedies	RoHS restricted substance") in exce if any, RoHS exemption you believe ing appropriate methods to ensure if ication in determining the complian form, and that Supplier may not have e provided certifications regarding the to the identified part, the terms and cc for issues that arise regarding inform	ce of its products with European Union membe	ove. If a homogeneous material within the part er level components, the declaration shall l correct to the best of its knowledge and belief, r state laws that implement the RoHS Directive. wever, in situations where Supplier has not tions are at least as comprehensive as the anty rights and/or remedies provided as part of						
RoHS Declaration * 1 - Item(s)	does not contain RoHS restricted substa	on above	Supplier Acceptance	* Accepted							
Exemption: If the declared item does not con applicable exemptions.	ntain RoHS restricted substances per	the definition above	except for defined RoHS exempti	ons, then select the corresponding response i	n the RoHS Declaration above and choose all						
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
Instructions: Complete all of the required fin Requester) and click on Submit Form to have	elds on all pages of this form. Select the form returned to the Requester	he "Accepted" on th	e Supplier Acceptance drop-down	. This will display the signature area. Digital	lly sign the declaration (if required by the						
Supplier Digital Signature Ra	stislav Drska	Le									

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Coupling Gel	0.4	mg	Supplier	Dimethyl Cyclosiloxanes	69430-24-6		0.04	mg
			Supplier	Trimethoxy(methyl)silane (C4H12O3Si)	1185-55-3		0.36	mg
Die	5.13	mg	Supplier	Silicon (Si)	7440-21-3		5.13	mg
Die Attach	0.3	mg	Supplier	Silver (Ag)	7440-22-4		0.225	mg
			Supplier	Phenolic Resin-2	54208-63-8		0.075	mg
Lead Frame 1	101.703	mg	Supplier	Silver (Ag)	7440-22-4		0.407	mg
			Supplier	Zinc (Zn)	7440-66-6		0.203	mg
			Supplier	Iron (Fe)	7439-89-6		2.64	mg
			Supplier	Copper (Cu)	7440-50-8		98.3	mg
			Supplier	Phosphorus (P)	7723-14-0		0.153	mg
Mold Compound-White	327.22	mg	Supplier	Titanium Dioxide (TiO2)	13463-67-7		81.805	mg
			В	Brominated Bisphenol A Diglycidyl Ether	40039-93-8		9.8166	mg
			Supplier	Ortho Cresol Novolac Resin	29690-82-2		44.1747	mg
			В	Antimony Trioxide (Sb2O3)	1309-64-4		9.8166	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		163.61	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		17.9971	mg
Plating	28.5	mg	Supplier	Tin (Sn)	7440-31-5		28.5	mg
Wire Bond - Au	1.65	mg	Supplier	Gold (Au)	7440-57-5		1.65	mg